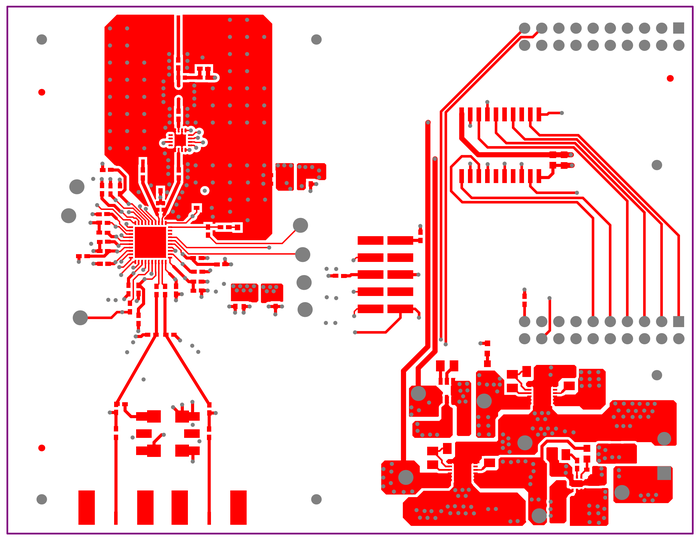
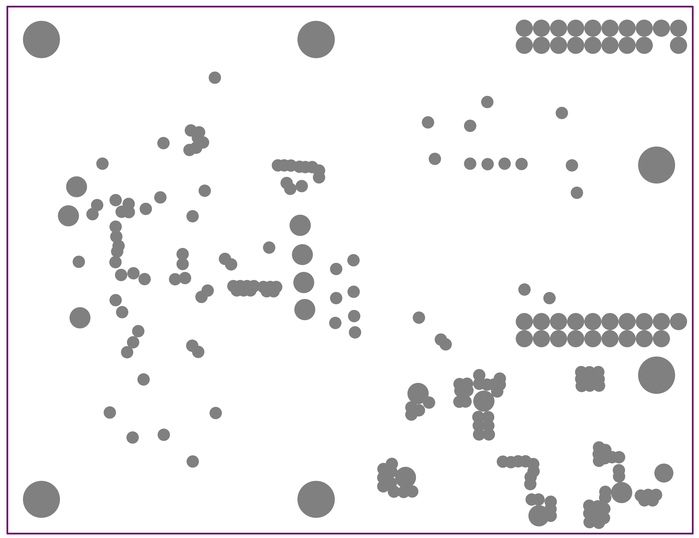
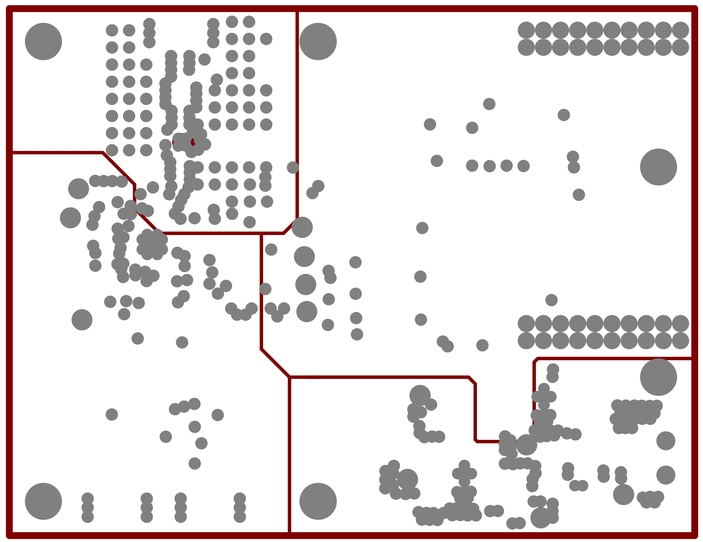


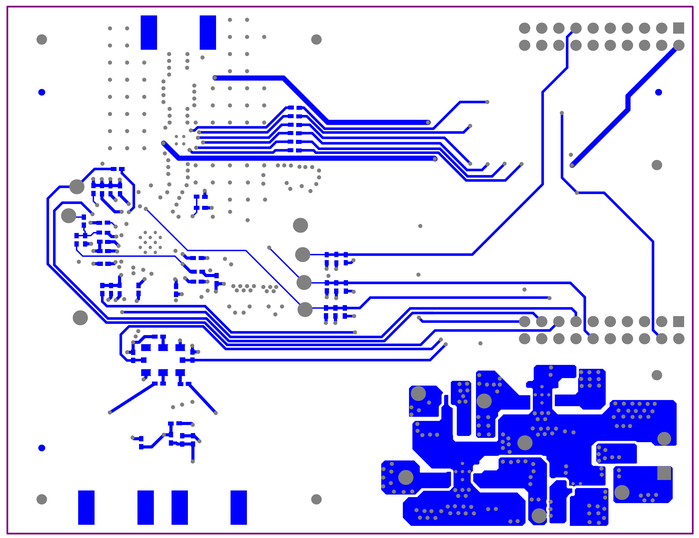
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00626		
PLOT NAME = Top Layer	GENERATED : 5/6/2016 2:17:37 PM		TEXAS INSTRUMENTS



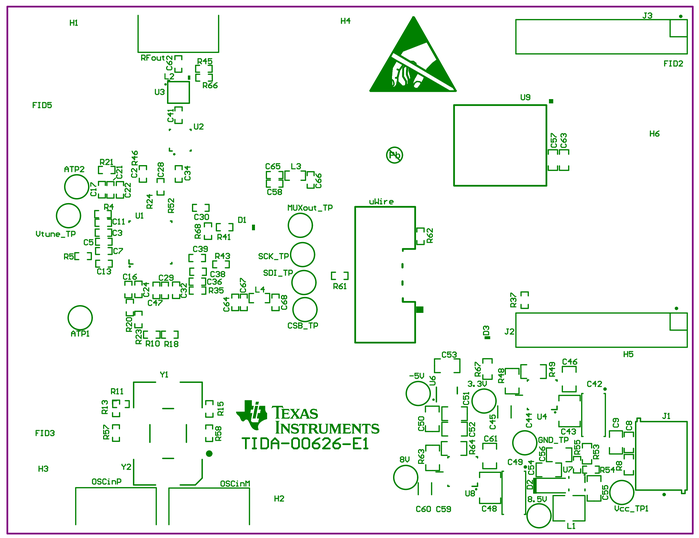
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-00626		
PLOT NAME = GND (GND1)	GENERATED : 5/6/2016 2:17:37 PM		TEXAS INSTRUMENTS



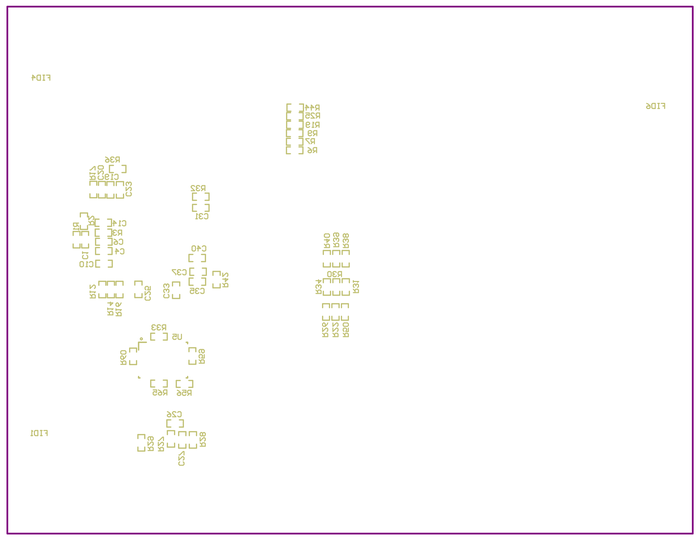
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = POWER	TID #: TIDA-00626		
PLOT NAME = POWER ((Multiple Nets))	GENERATED : 5/6/2016 2:17:37 PM		TEXAS INSTRUMENTS



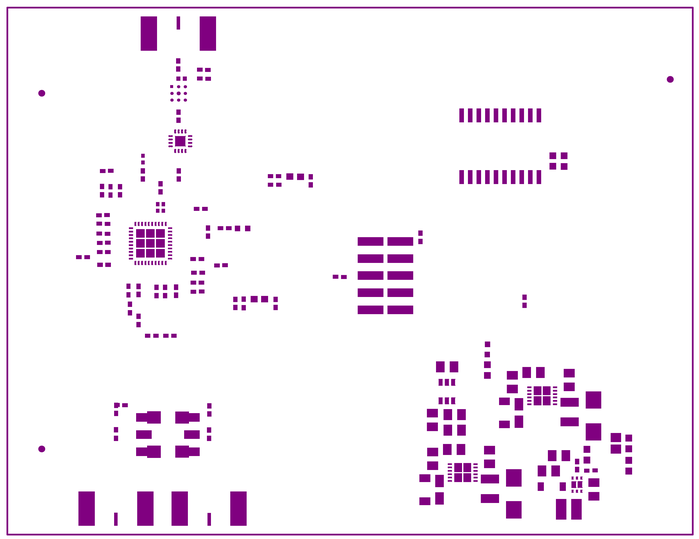
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00626		
PLOT NAME = Bottom Layer	GENERATED : 5/6/2016 2:17:37 PM		TEXAS INSTRUMENTS



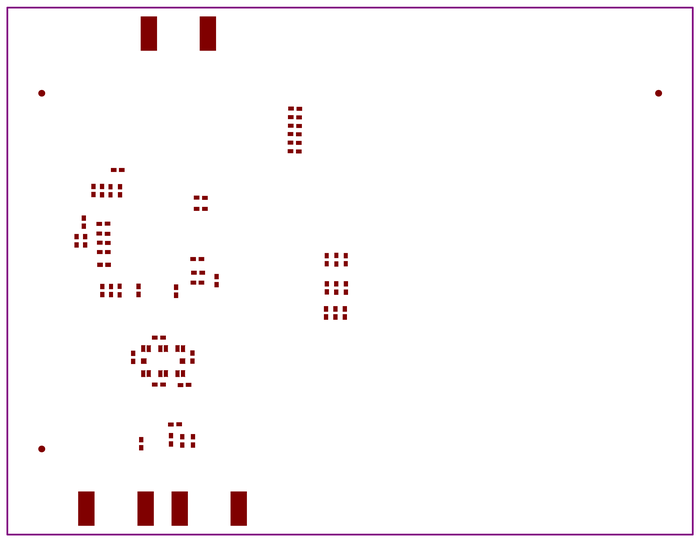
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00626		
PLOT NAME = Top Silkscreen Overlay	GENERATED : 5/6/2016 2:17:38 PM		TEXAS INSTRUMENTS



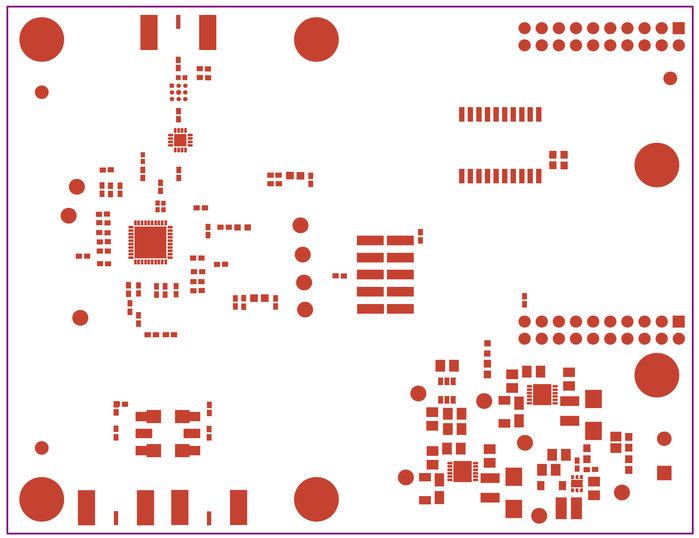
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00626		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 5/6/2016 2:17:38 PM		TEXAS INSTRUMENTS



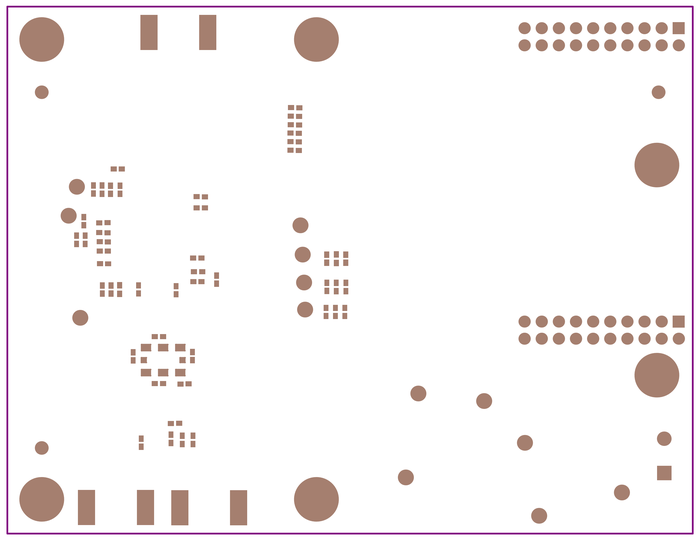
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDA-00626		
PLOT NAME = Top Paste Mask Print	GENERATED : 5/6/2016 2:17:38 PM		TEXAS INSTRUMENTS



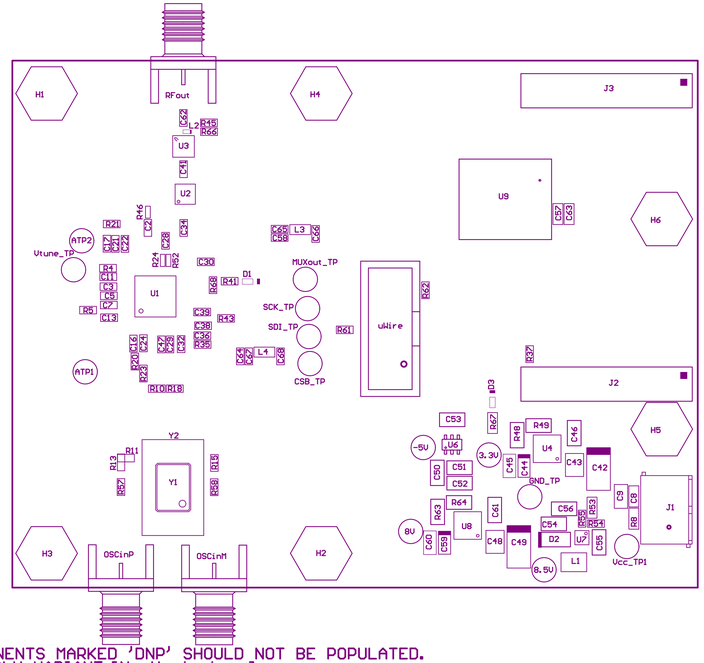
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDA-00626		
PLOT NAME = Bottom Paste Mask Print	GENERATED : 5/6/2016 2:17:38 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00626		
PLOT NAME = Top Solder Mask Print	GENERATED : 5/6/2016 2:17:39 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00626		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 5/6/2016 2:17:39 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT:[No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
IGNORE -> M5 Assembly Top	TID #: TIDA-00626		
PLOT NAME = M5 Assembly Top	GENERATED : 5/6/2016 2:17:39 PM		TEXAS INSTRUMENTS

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PLOT NAME = M6 Assembly Bottom	GENERATED : 5/6/2016 2:17:39 PM		TEXAS INSTRUMENTS
	TID #: TIDA-00626 IGNORE -> M6 Assembly Bottom		
PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl

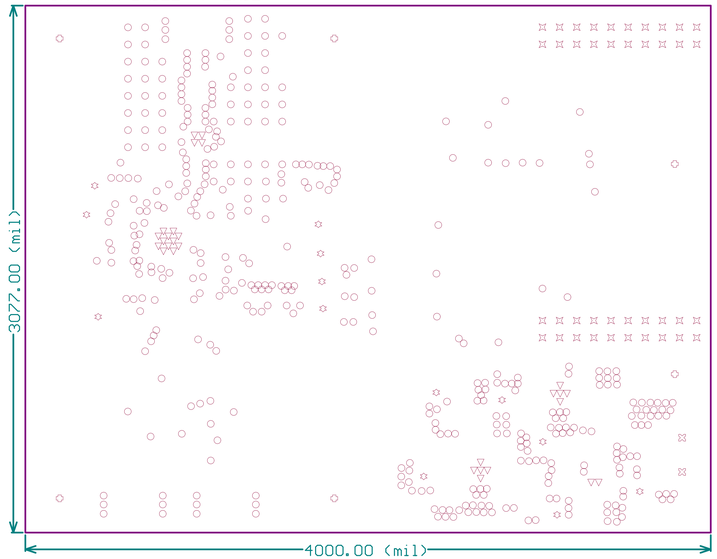
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	Rogers4003C	9.50mil	4.8	
5	GND	Copper	1.40mil		
6	Dielectric 3	FR-4	35.00mil	4.8	
7	POWER	Copper	1.40mil		
8	Dielectric 2	FR-4	9.50mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

20mils width on top layer should be controlled 50 ohms +/- 5%

Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	28	7.874mil (0.2mm)	PTH	Round
○	420	12mil (0.305mm)	PTH	Round
⌑	40	40mil (1.016mm)	PTH	Round
⊠	2	51.181mil (1.3mm)	PTH	Round
☼	13	63mil (1.6mm)	PTH	Round
◌	6	157mil (3.988mm)	NPTH	Round
	509 Total			

Drill Table

FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL



DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
4000MIL X 3077MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.69 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[X] FR-408 [ ] FR4 High Tg [X] RO4003C
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

Note: Not put solder on U1 (LMX2592 IC) footprint if IC is not installed.

TEXAS INSTRUMENTS

PROJECT TITLE: CW RF SIGNAL GENERATOR
DESIGNED FOR: Public Release
FILE NAME: TIDA-00626.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00626		
PLOT NAME = Drill Drawing	GENERATED : 5/6/2016 2:17:39 PM	TEXAS INSTRUMENTS	

ENGINEER: Skariah, Leni	LAYOUT BY: Manjunatha T N
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.14.34663

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